Replacement Specification Paragraphs

Please amend the numbered paragraphs below as follows:

[0001] This application is a Continuation-In-Part of U.S. Patent Application Serial No. 10/336,130, filed January 3, 2003~~and now pending~~, which issued as U.S. Patent No. 6,764,419 on July 20, 2004, and which is incorporated herein by reference.

[0038] The bond-inhibiting layer 30 preferably has a radial thickness of approximately 0.001 to 0.004 inches, more preferably 0.002 to 0.003 inches. The bond inhibiting layer is preferably made of a ~~Teflon material~~ fluoropolymer, such as FEP (fluorinated ethylene propylene), PVF (Polyvinyl Fluoride), ETFE (EthyleneTetrafluoroethylene), PCTFE (PolyChloroTriFluoroEthylene), or PTFE/Teflon® (Polytetraflouroethylene), and/or another material, such as PMP (Polymethylpentene), ~~PVF (Polyvinyl Fluoride),~~ Nylon (~~polyamideimide~~ polyamide), or Cellophane. Other ISCZs, such as a friction joint, a sliding joint, or an elastomeric joint, may be used as an alternative to the bond inhibiting layer 30. The bond inhibiting layer 30, or other ISCZ, may be located at the radial midpoint of the barrel 14, such that each barrel wall 22, 24 has approximately the same radial thickness, or it may be located elsewhere in the barrel 14. Thus, the bond-inhibiting layer 30 is shown at the approximate radial midpoint of the barrel 14 by way of example only.